ON Semiconductor®

Product Bulletin

Document # :PB21821Z
Issue Date: 22 August 2017

Title of Change:	Improved SOT5X3 cross bar of carrier tape at ON Semiconductor, Leshan, China factory.
Effective date:	22 August 2017
Contact information:	Contact your local ON Semiconductor Sales Office or <Coleen.Long@onsemi.com>
Type of notification:	ON Semiconductor will consider this change accepted.
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☒ Other Cross Bar of Carrier Tape Change

Change Sub-Category(s):

☐ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☒ Shipping/Packaging/Marking
☐ Other:

Sites Affected:

☐ All site(s) ☐ not applicable ☒ ON Semiconductor site(s) : ON Leshan, China ☐ External Foundry/Subcon site(s)

Description and Purpose:

Improved SOT5X3 cross bar of carrier tape to eliminate potential risk of unit rotate in tape. All new product releases currently incorporate this type of carrier tape and products listed in this product bulletin are being converted after the proposed ship date.

The MPQ, reel size and cover tape dimension have no changes. There does not require any modifications to the assembly processes or flows.

There is no change to the form, fit, or function of the physical part.

List of Affected Standard Parts:

NSV12100XV6T1G	NSVEMD4DXV6T5G
NSVB143ZPDXV6T1G	NSVEMT1DXV6T1G
NSVBA114EDXV6T1G	NSVEMT1DXV6T5G
NSVBA114YDXV6T1G	NSVEMX1DXV6T1G
NSVBAV70DXV6T5G	NSVR0320XV6T1G
NSVBC114EDXV6T1G	NSVT30010MXV6T1G
NSVBC114EPDXV6T1G	NSVT3904DXV6T1G
NSVBC114YDXV6T1G	NSVT3906DXV6T1G
NSVBC114YPDXV6T1G	NSVT3946DXV6T1G
NSVBC123JPDXV6T1G	SBC847BPDXV6T1G
NSVBC124EDXV6T1G	SBC847CDXV6T1G
NSVBC124XPDXV6T1G	SNST3904DXV6T5G
NSVBC143TPDXV6T1G	SZNUP4060AXV6T1G
NSVBC143ZPDXV6T1G	SZNZQA5V6AXV5T1G
NSVBC143ZPDXV6T5G	SZQA6V8XV5T1G
NSVBC144EPDXV6T1G	
NSVEMC2DXV5T1G	